## Designer's™ Data Sheet

# Insulated Gate Bipolar Transistor with Anti-Parallel Diode

## N-Channel Enhancement-Mode Silicon Gate

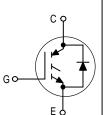
This Insulated Gate Bipolar Transistor (IGBT) is co-packaged with a soft recovery ultra-fast rectifier and uses an advanced termination scheme to provide an enhanced and reliable high voltage-blocking capability. Short circuit rated IGBT's are specifically suited for applications requiring a guaranteed short circuit withstand time such as Motor Control Drives. Fast switching characteristics result in efficient operations at high frequencies. Co-packaged IGBT's save space, reduce assembly time and cost.

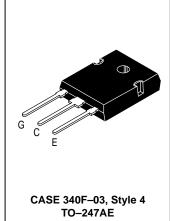
- Industry Standard High Power TO–247 Package with Isolated Mounting Hole
- High Speed E<sub>off</sub>: 60 μJ per Amp typical at 125°C
- High Short Circuit Capability 10 μs minimum
- Soft Recovery Free Wheeling Diode is included in the package
- Robust High Voltage Termination
- Robust RBSOA

## MGW20N60D

Motorola Preferred Device

IGBT & DIODE IN TO-247 20 A @ 90°C 32 A @ 25°C 600 VOLTS SHORT CIRCUIT RATED





### **MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCES	600	Vdc
Collector–Gate Voltage (R <sub>GE</sub> = 1.0 MΩ)	VCGR	600	Vdc
Gate-Emitter Voltage — Continuous	V <sub>GE</sub>	±20	Vdc
Collector Current — Continuous @ T <sub>C</sub> = 25°C — Continuous @ T <sub>C</sub> = 90°C — Repetitive Pulsed Current (1)	I <sub>C25</sub> I <sub>C90</sub> I <sub>CM</sub>	32 20 64	Adc Apk
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	PD	142 1.14	Watts W/°C
Operating and Storage Junction Temperature Range	TJ, T <sub>stg</sub>	-55 to 150	°C
Short Circuit Withstand Time (V <sub>CC</sub> = 360 Vdc, V <sub>GE</sub> = 15 Vdc, T <sub>J</sub> = 25°C, R <sub>G</sub> = 20 $\Omega$ )	t <sub>sc</sub>	10	μs
Thermal Resistance — Junction to Case – IGBT — Junction to Case – Diode — Junction to Ambient	R <sub>θ</sub> JC R <sub>θ</sub> JC R <sub>θ</sub> JA	0.88 2.00 45	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C
Mounting Torque, 6–32 or M3 screw	10 lbf•in (1.13 N•m)		

<sup>(1)</sup> Pulse width is limited by maximum junction temperature.

**Designer's Data for "Worst Case" Conditions** — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

Preferred devices are Motorola recommended choices for future use and best overall value



## MGW20N60D

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector-to-Emitter Breakdown	BVCES	000			Vdc	
$(V_{GE}=0\ Vdc,\ I_{C}=250\ \mu Adc)$ Temperature Coefficient (Positive)			600	870	_	mV/°C
Zero Gate Voltage Collector Curr (VCE = 600 Vdc, VGE = 0 Vdc	ICES	_	_	100	μAdc	
$(V_{CE} = 600 \text{ Vdc}, V_{GE} = 0 \text{ Vdc})$		_	_	2500		
Gate–Body Leakage Current (VGE = ± 20 Vdc, VCE = 0 Vdc)		IGES	_	_	250	nAdc
ON CHARACTERISTICS (1)				_		1
Collector–to–Emitter On–State V (VGE = 15 Vdc, IC = 10 Adc)	oltage	VCE(on)	l _	2.30	2.85	Vdc
(VGE = 15 Vdc, IC = 10 Adc, T	J = 125°C)		_	2.20		
(V <sub>GE</sub> = 15 Vdc, I <sub>C</sub> = 20 Adc)			_	2.85	3.65	
Gate Threshold Voltage		VGE(th)		0.0	0.0	Vdc
(V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1 mAdc) Threshold Temperature Coeffice	sient (Negative)		4.0	6.0 10	8.0 —	mV/°C
Forward Transconductance (VCE	= 10 Vdc, I <sub>C</sub> = 20 Adc)	9fe	<u> </u>	12	_	Mhos
DYNAMIC CHARACTERISTICS	-		<u> </u>		<u> </u>	l
Input Capacitance		C <sub>ies</sub>	_	2280	_	pF
Output Capacitance	$V_{CE} = 25 \text{ Vdc}, V_{GE} = 0 \text{ Vdc},$ f = 1.0  MHz)	C <sub>oes</sub>	_	165	_	1
Transfer Capacitance	1 - 1.0 Wil 12)	C <sub>res</sub>	<u> </u>	12	_	
SWITCHING CHARACTERISTICS	<del>(</del> (1)	•		•		
Turn-On Delay Time		<sup>t</sup> d(on)	_	59	_	ns
Rise Time	(V <sub>CC</sub> = 360 Vdc, I <sub>C</sub> = 20 Adc, V <sub>GE</sub> = 15 Vdc, L = 300 μH	t <sub>r</sub>	_	61	_	1
Turn-Off Delay Time	$R_G = 20 \Omega, T_J = 25^{\circ}C$	td(off)	_	150	_	1
Fall Time	Energy losses include "tail"	t <sub>f</sub>	_	212	_	1
Turn-Off Switching Loss	7	E <sub>off</sub>	_	0.60	0.85	mJ
Turn-On Switching Loss	7	E <sub>on</sub>	_	0.75	_	1
Total Switching Loss	7	E <sub>ts</sub>	_	1.35	_	
Turn-On Delay Time	0/4 000 V/4 1 00 A 4	<sup>t</sup> d(on)	_	51	_	ns
Rise Time	V <sub>CC</sub> = 360 Vdc, I <sub>C</sub> = 20 Adc, V <sub>GE</sub> = 15 Vdc, L = 300 μH	t <sub>r</sub>	_	77	_	
Turn-Off Delay Time	$R_G = 20 \Omega, T_J = 125^{\circ}C)$	td(off)	_	184	_	1
Fall Time	Energy losses include "tail"	t <sub>f</sub>	_	392	_	1
Turn-Off Switching Loss	7	E <sub>off</sub>	_	1.20	_	mJ
Turn-On Switching Loss	7	E <sub>on</sub>	_	1.50	_	1
Total Switching Loss	7	E <sub>ts</sub>	_	2.70	_	1
Gate Charge		QT	_	74	_	nC
	(V <sub>CC</sub> = 360 Vdc, I <sub>C</sub> = 20 Adc, V <sub>GE</sub> = 15 Vdc)	Q <sub>1</sub>	_	19	_	1
vGE = 15 vdc)		Q <sub>2</sub>	_	27	_	
DIODE CHARACTERISTICS	•	ı	•	•		
Diode Forward Voltage Drop		V <sub>FEC</sub>				Vdc
(IEC = 10 Adc)		-	1.50	1.90		
(I <sub>EC</sub> = 10 Adc, T <sub>J</sub> = 125°C) (I <sub>EC</sub> = 20 Adc)			1.30 1.70	 2.15		

(1) Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

(continued)

## **ELECTRICAL CHARACTERISTICS** — **continued** (T<sub>J</sub> = 25°C unless otherwise noted)

Cha	Symbol	Min	Тур	Max	Unit		
DIODE CHARACTERISTICS — continued							
Reverse Recovery Time		t <sub>rr</sub>	_	117	_	ns	
	$(I_F = 20 \text{ Adc}, V_R = 360 \text{ Vdc}, \\ dI_F/dt = 200 \text{ A}/\mu\text{s})$	ta	_	70	_		
		t <sub>b</sub>	_	47	_		
Reverse Recovery Stored Charge		Q <sub>RR</sub>	_	1.2	_	μС	
Reverse Recovery Time			_	166	_	ns	
	(I <sub>F</sub> = 20 Adc, V <sub>R</sub> = 360 Vdc, dI <sub>F</sub> /dt = 200 A/µs, T <sub>J</sub> = 125°C)	t <sub>a</sub>	_	98	_		
		t <sub>b</sub>	_	68	_		
Reverse Recovery Stored Charge		Q <sub>RR</sub>	_	1.9	_	μС	
NTERNAL PACKAGE INDUCTANCE							
Internal Emitter Inductance (Measured from the emitter lead 0.25" from package to emitter bond pad)		LE	_	13	_	nH	

## TYPICAL ELECTRICAL CHARACTERISTICS

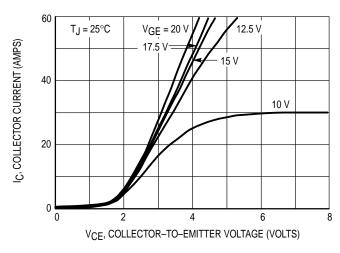


Figure 1. Output Characteristics, T<sub>J</sub> = 25°C

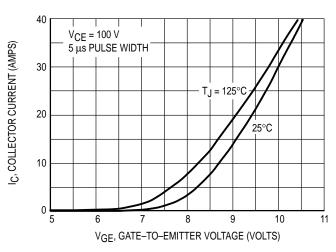


Figure 3. Transfer Characteristics

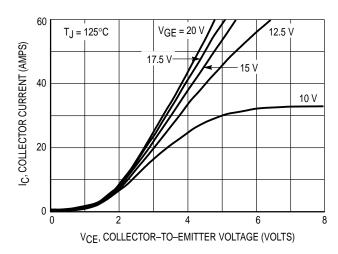


Figure 2. Output Characteristics, T<sub>J</sub> = 125°C

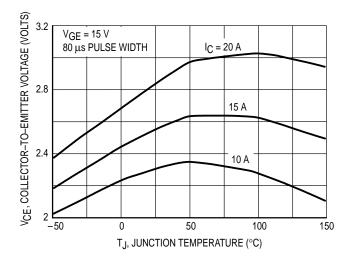


Figure 4. Collector-to-Emitter Saturation Voltage versus Junction Temperature

## MGW20N60D

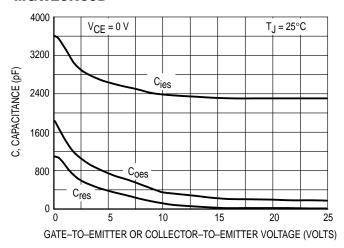


Figure 5. Capacitance Variation

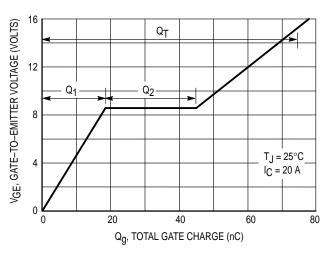


Figure 6. Gate-to-Emitter Voltage versus
Total Charge

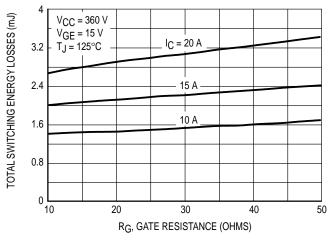


Figure 7. Total Switching Losses versus
Gate Resistance

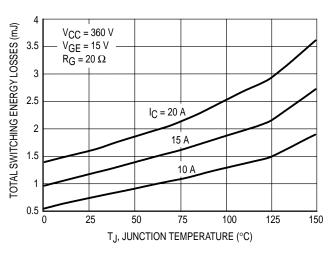


Figure 8. Total Switching Losses versus Junction Temperature

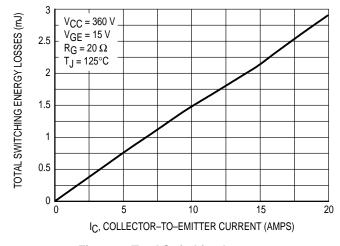


Figure 9. Total Switching Losses versus Collector-to-Emitter Current

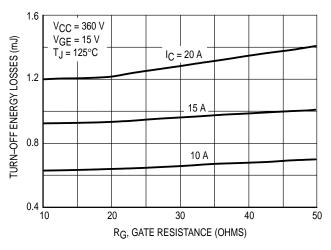
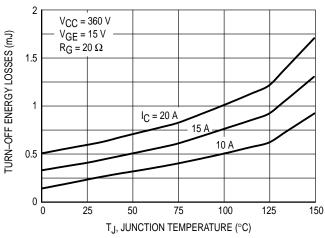


Figure 10. Turn-Off Losses versus
Gate Resistance



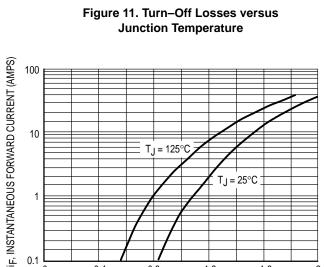


Figure 13. Typical Diode Forward Drop versus Instantaneous Forward Current

V<sub>FM</sub>, FORWARD VOLTAGE DROP (VOLTS)

1.2

0.4

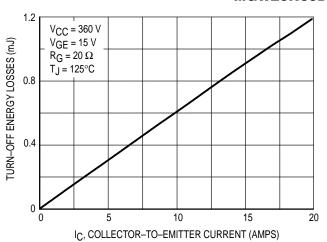


Figure 12. Turn-Off Losses versus Collector-to-Emitter Current

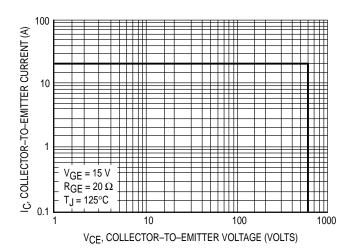
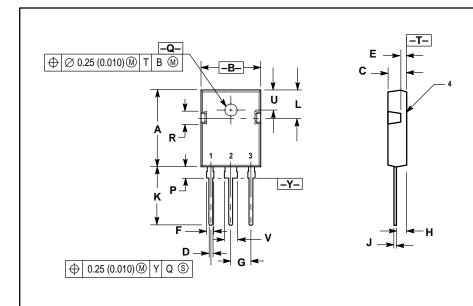


Figure 14. Reverse Biased Safe Operating Area

#### PACKAGE DIMENSIONS

CASE 340F-03 TO-247AE **ISSUE E** 



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	20.40	20.90	0.803	0.823	
В	15.44	15.95	0.608	0.628	
С	4.70	5.21	0.185	0.205	
D	1.09	1.30	0.043	0.051	
Е	1.50	1.63	0.059	0.064	
F	1.80	2.18	0.071	0.086	
G	5.45 BSC		0.215 BSC		
Н	2.56	2.87	0.101	0.113	
J	0.48	0.68	0.019	0.027	
K	15.57	16.08	0.613	0.633	
L	7.26	7.50	0.286	0.295	
Р	3.10	3.38	0.122	0.133	
Q	3.50	3.70	0.138	0.145	
R	3.30	3.80	0.130	0.150	
U	5.30 BSC		0.209 BSC		
V	3.05	3 40	0.120	0.134	

STYLE 4: PIN 1. GATE

- 2. COLLECTOR 3. EMITTER
- 4. COLLECTOR

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Motorola data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical parameters, including or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and 👭 are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

#### How to reach us:

USA/EUROPE/Locations Not Listed: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036. 1-800-441-2447 or 602-303-5454

MFAX: RMFAX0@email.sps.mot.com - TOUCHTONE 602-244-6609 INTERNET: http://Design-NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, 6F Seibu-Butsuryu-Center, 3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-81-3521-8315

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298



